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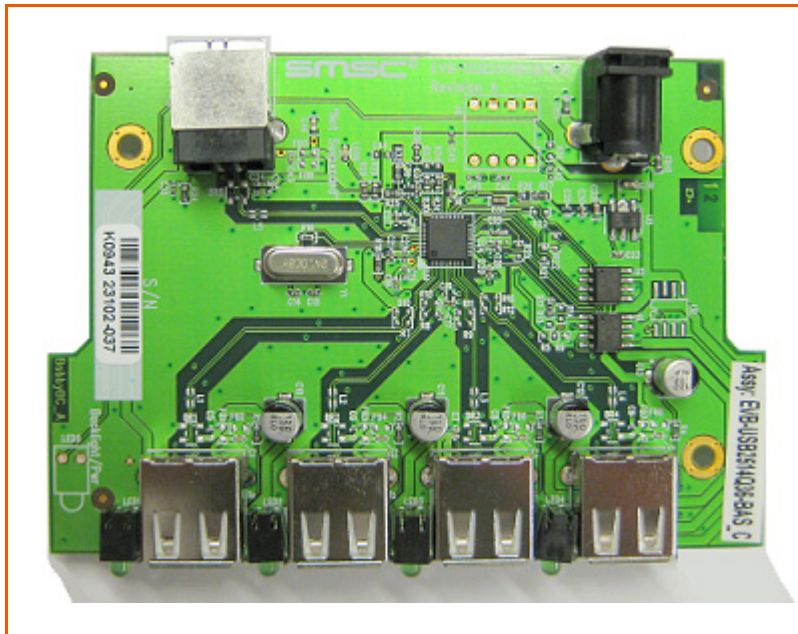
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EVB-USB2514Q36-BAS, USB2513 and USB2512 36-Pin QFN Evaluation Board, Revision C User Manual



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1 Overview

The SMSC USB2514 MultiTRAK™ is a Low-Power, full featured Hi-Speed USB 2.0 compliant hub with four down-stream ports. The EVB-USB2514Q36-BAS Evaluation Board demonstrates a stand alone application for the hub with all the features listed below and demonstrates the advanced power saving options and configurable port assignments. Two other versions of the evaluation board are available using the same printed circuit board (PCB) populated with either the USB2512, 2-port hub or the USB2513, 3-port hub with part numbers EVB-USB2512Q36-BAS and EVB-USB2513Q36-BAS. The PCB is labeled EVB-USB2514BCQFN36, Revision A for all assembly versions.

1.1 Features

- Low pin count USB2514 36 - pin QFN package
 - USB2512: 2-port version
 - USB2513: 3-port version
- Hi-Speed (480 Mbits/s), Full-Speed (12 Mbits/s), and Low-Speed (1.5 Mbits/s) compatible.
- Operates from a single voltage (+5.0 VDC, regulated) 'wall wart' external power supply.
- Low cost 4-layer design: two outer signal layers
 - power inner layers
 - ground inner layers
- Optional pull-up resistors for disabling individual downstream ports.
- Self-powered operation.
- Multi-transaction translator enabled.
- Supports internal default hub configuration.
- Single onboard +3.3 VDC regulator.
- A footprint is provided for alternate regulator for industrial temperature operation.
- Single crystal clock source.
- Individual port over-current sensing.
- Individual port power control.
- Port overcurrent sensing (OCS)/port power control interface with LEDs for port power indication.
- Red LED indicator for active hub state (not suspend).
- EMI suppression provided by ferrite beads, selection of capacitors, and internal power/ground layers.
- ESD protection up to 25 kV direct contact to USB signals provided with diode bridges and common mode chokes.

1.2 General Description

The EVB-USB2514Q36-BAS is a demonstration and low-cost evaluation platform featuring the USB2514 MultiTRAK™ 4-port, Low-Power High-Speed USB2.0 Hub. It is designed to robustly demonstrate the unique features of this device using a low-cost PCB implementation with individual port power control. The EVB-USB2514 is designed for low cost, power efficient implementation of a Hi-speed USB Hub with minimal bill of materials. Schematics, layout, and bill of materials are included minimizing the customers new product development time.

Revision C of the EVB-USB2514Q36-BAS has a four-layer printed circuit board to improve coupling between power and ground to reduce EMI. Ferrite beads have been added on all connector ground and power nets. Protective diode bridges and common mode chokes were added to all USB signals.

[Figure 2.1](#) and [Figure 2.2](#) show the top and bottom level silk screen and copper layers.

2 Hardware Configuration

2.1 Hardware Description

The EVB-USB2514Q36-BAS has one onboard regulator, which generates +3.3 VDC from a +5.0 VDC power supply. An alternate footprint U5 was added to support industrial temperature range. The alternate footprint supports a larger package and has ties into the ground plane for better thermal dissipation. The USB2514 generates its own on-chip +1.8 VDC supply. The USB2514 Hub consumes power from the +3.3 VDC supply while the MIC2026 Power distribution switch consumes power from the +5.0 VDC supply. The MIC2026 Power distribution switch supplies downstream power to each attached device.

2.1.1 Port Assignment

Downstream ports are numbered 1 through 4 with individual port power controllers. The port power controllers provide 5 Volt power with over-current protection to the downstream devices. Upstream and downstream port connectors have USB 2.0 compliant decoupling, filtering for EMI on signal ground and power, and a separate shield ground. ESD protection for USB signals is provided by diode bridges and common mode chokes. This gives protection up to 25 kV direct contact to USB signals.

Optional pull-up resistors can be placed to disable a USB port, see the schematic on the CD-ROM included with your EVB-USB2514Q36-BAS for implementation.

2.1.2 HUB Configuration

The EVB-USB2514Q36-BAS has been configured to support internal default configuration with strapping options enabled as determined by the state of CFG_SEL[1] and CFG_SEL[0] pins immediately after reset. The internal +1.8 VDC regulator supplies voltage to the oscillator and PLL is turned off during suspend to minimize suspend current.

2.1.3 Powered State LED

An optional LED (LED5) indicates when +5.0 VDC power is present.

2.1.4 Active State LED

An optional LED (LED6) indicates when the hub is active (configured and not suspended).

2.1.5 Port Power LEDs

LED1, LED2, LED3, and LED4 indicate when port power is available to the associated downstream USB port.

2.1.6 Connector Description

The EVB-USB2514Q36-BAS has a set of standard USB style connectors, one of type B for the upstream port and four of type A for downstream ports. Power is supplied via a 2.0 mm power jack. [Table 2.1](#) lists all of the connectors. For more details on the pinout of these connectors, please see the EVB-USB2514Q36-BAS schematics on the CD-ROM included with your EVB-USB2514Q36-BAS.

Table 2.1 Connector Description

CONNECTOR	TYPE	DESCRIPTION
J1	USB A	Downstream USB Port 1
J2	USB A	Downstream USB Port 2
J3	USB A	Downstream USB Port 3
J4	USB A	Downstream USB Port 4
J5	USB B	Upstream USB Port 0
J6	Power Jack 2.0 mm	+5.0 VDC Power Supply

2.1.7 Layout Considerations

The EVB-USB2514Q36-BAS is designed on four PCB layers—two signal layers and two supply layers. The PCB layer stackup is shown in [Table 2.2](#). All signals are routed on top and bottom layers. Internal layers are ground and power. Note that the differential signals from the USB2514 match the upstream and downstream port placement simplifying routing of critical signals.

Table 2.2 PCB layer stack

Component Side	
Solder mask	
Layer 1	1.9 - 2.8 mil, finished
Pre-preg	4.25 mil, +/- 0.25 mil FR-4
Layer 2 -- GND	1.3 mil (nominal)
Core	~24 mil FR-4
Layer 3 -- POWER	1.3 mil (nominal)
Pre-preg	4.25 mil, +/- 0.25 mil FR-4
Layer 4	1.9 - 2.8 mil, finished
Solder mask	
Solder Side	

Component side top layer is shown in Figure 2.1 with silk screen information to identify component locations.

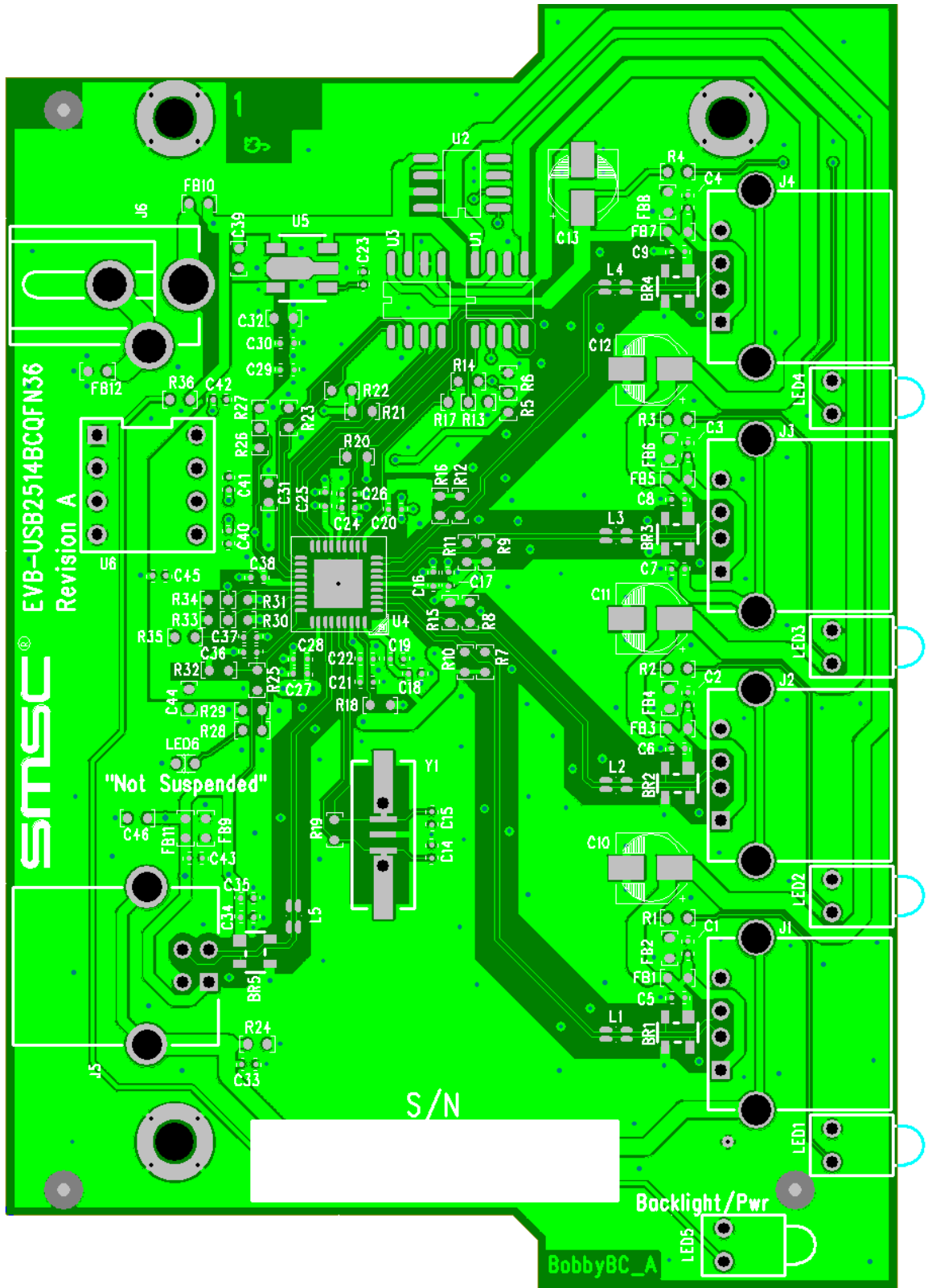


Figure 2.1 EVB-USB2514Q36-BAS Top Layer - Component Side

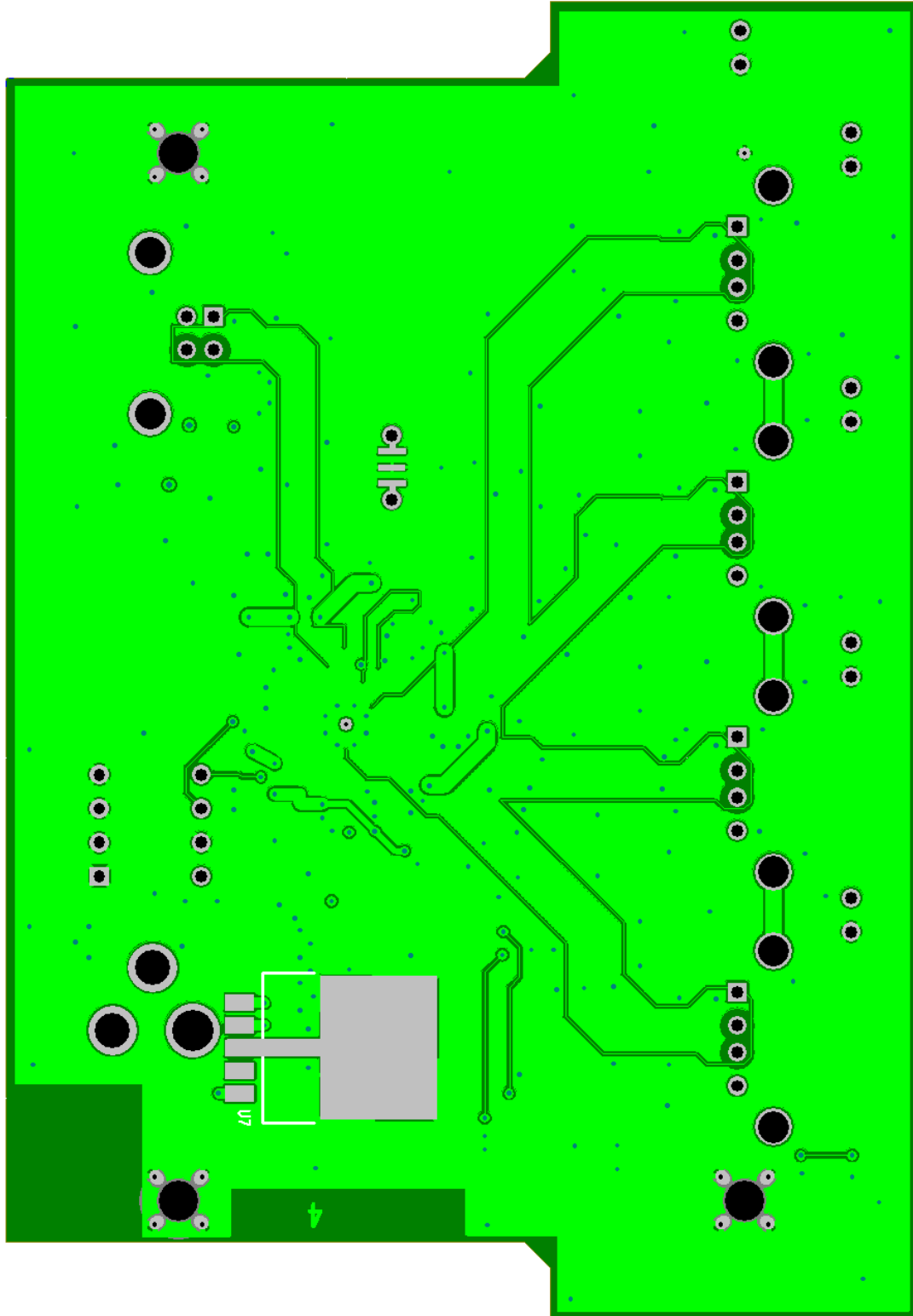


Figure 2.2 EVB-USB2514Q36-BAS Bottom Layer - Solder Side